

PMEG2020CPA

2 A low V_F dual MEGA Schottky barrier rectifier

Rev. 1 — 5 August 2010

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT1061 leadless small Surface-Mounted Device (SMD) plastic package with medium power capability.

1.2 Features and benefits

- Average forward current: $I_{F(AV)} \leq 2$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage
- Exposed heat sink (cathode pad) for excellent thermal and electrical conductivity
- Leadless small SMD plastic package with medium power capability
- AEC-Q101 qualified

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Battery chargers for mobile equipment

1.4 Quick reference data

Table 1. Quick reference data
 $T_j = 25$ °C unless otherwise specified.

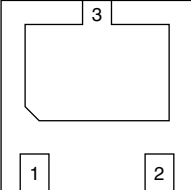
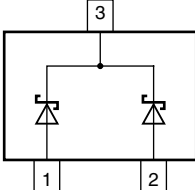
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz				
		$T_{amb} \leq 80$ °C	[1]	-	2	A
		$T_{sp} \leq 140$ °C	-	-	2	A
V_R	reverse voltage		-	-	20	V
V_F	forward voltage	$I_F = 2$ A	-	385	420	mV
I_R	reverse current	$V_R = 20$ V	-	380	1000	μ A

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode diode 1	 <p>Transparent top view</p>	 <p>006aaa438</p>
2	anode diode 2		
3	common cathode		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2020CPA	HUSON3	plastic thermal enhanced ultra thin small outline package; no leads; three terminals; body 2 × 2 × 0.65 mm	SOT1061

4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2020CPA	AL

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
Per diode						
V_R	reverse voltage	$T_j \leq 25\text{ °C}$	-	20	V	
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20\text{ kHz}$				
		$T_{amb} \leq 80\text{ °C}$	[1]	-	2	A
		$T_{sp} \leq 140\text{ °C}$	-	-	2	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$	-	7	A	
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8\text{ ms}$	[2]	-	9	A

Table 5. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
Per device, one diode loaded						
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[3][4]	-	500	mW
			[3][5]	-	960	mW
			[1][3]	-	1800	mW
T_j	junction temperature		-	150	°C	
T_{amb}	ambient temperature		-55	+150	°C	
T_{stg}	storage temperature		-65	+150	°C	

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.[2] $T_j = 25\text{ °C}$ prior to surge.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[5] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Per device, one diode loaded							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]				
			[3]	-	-	250	K/W
			[4]	-	-	130	K/W
			[5]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	12	K/W

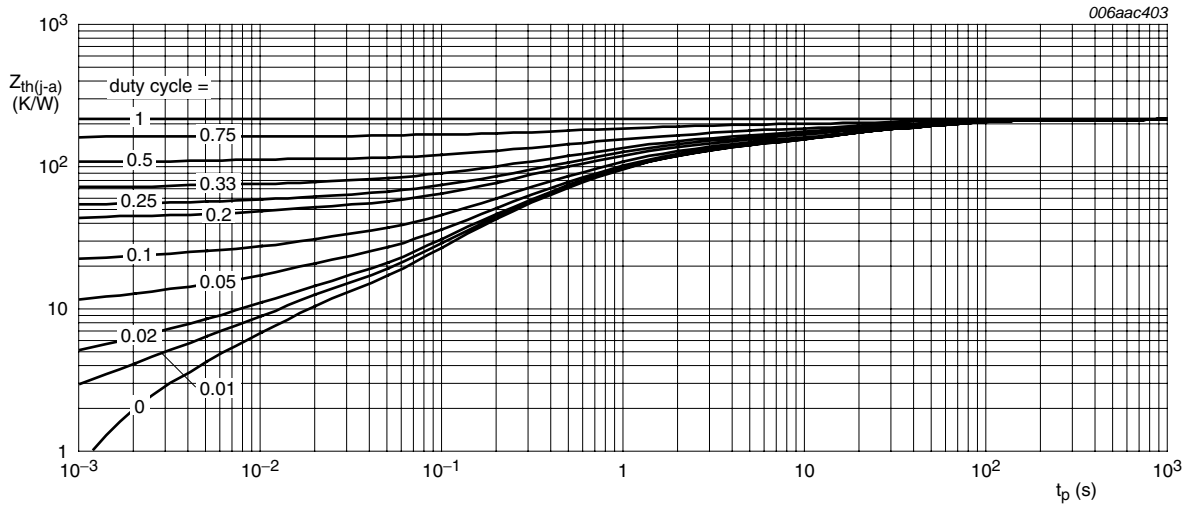
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

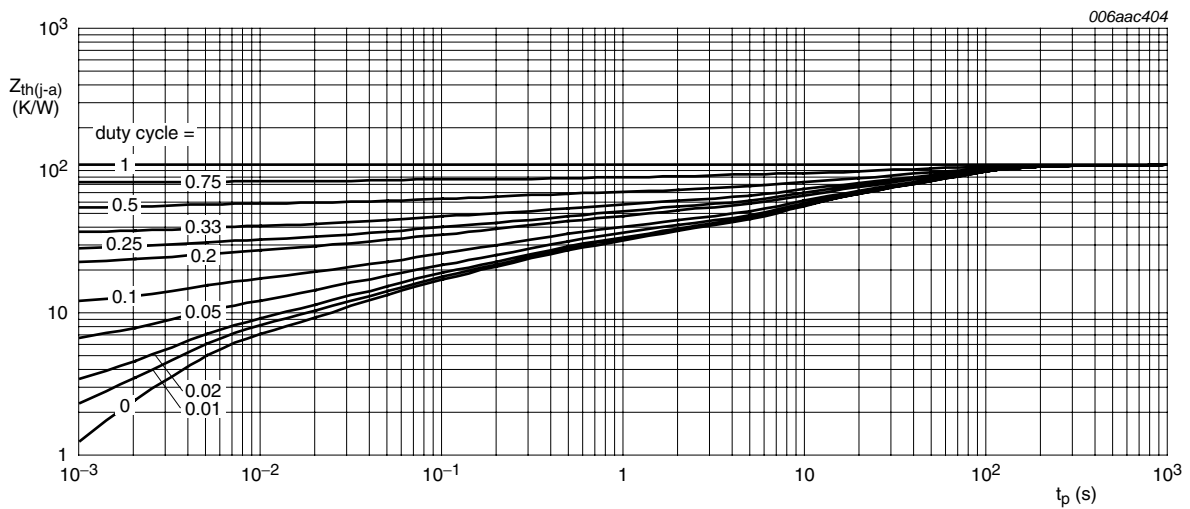
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .[5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[6] Soldering point of cathode tab.



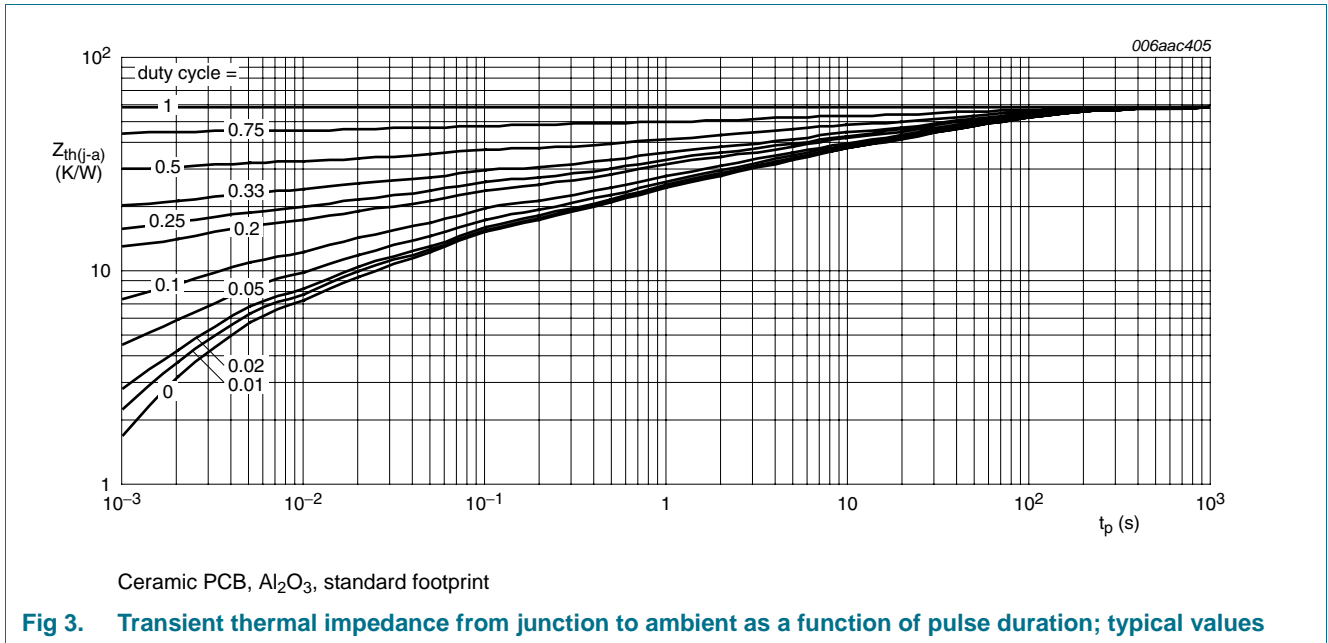
FR4 PCB, standard footprint

Fig 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

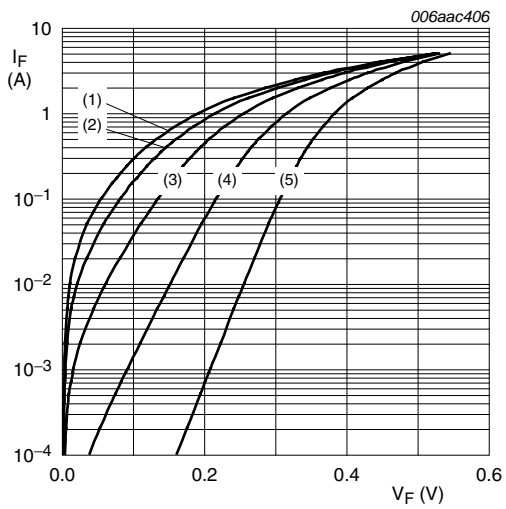


7. Characteristics

Table 7. Characteristics
 $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

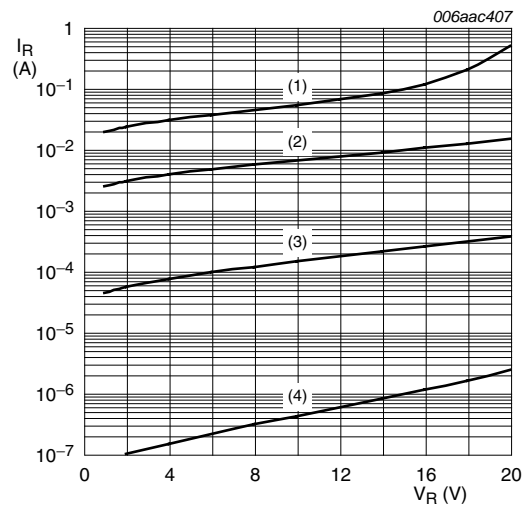
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	$I_F = 100\text{ mA}$	-	220	-	mV
		$I_F = 1\text{ A}$	-	320	360	mV
		$I_F = 2\text{ A}$	-	385	420	mV
I_R	reverse current	$V_R = 10\text{ V}$	-	160	-	μA
		$V_R = 20\text{ V}$	-	380	1000	μA
C_d	diode capacitance	$f = 1\text{ MHz}$				
		$V_R = 1\text{ V}$	-	175	-	pF
		$V_R = 10\text{ V}$	-	65	-	pF
t_{rr}	reverse recovery time		[1]	55	-	ns

[1] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 1\text{ mA}$.



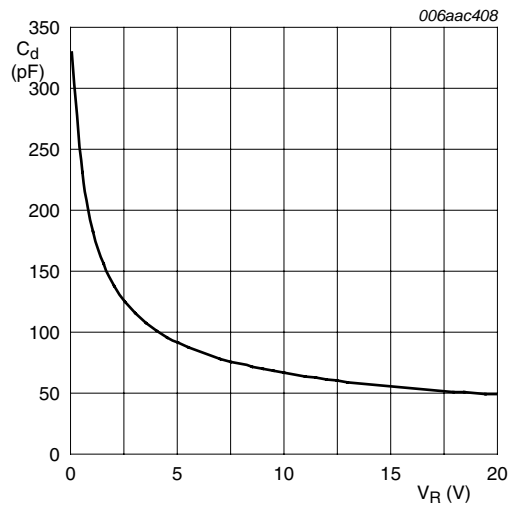
- (1) $T_j = 150\text{ °C}$
- (2) $T_j = 125\text{ °C}$
- (3) $T_j = 85\text{ °C}$
- (4) $T_j = 25\text{ °C}$
- (5) $T_j = -40\text{ °C}$

Fig 4. Forward current as a function of forward voltage; typical values



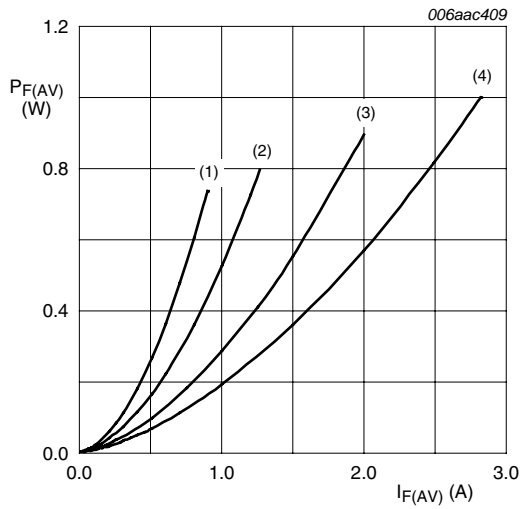
- (1) $T_j = 125\text{ °C}$
- (2) $T_j = 85\text{ °C}$
- (3) $T_j = 25\text{ °C}$
- (4) $T_j = -40\text{ °C}$

Fig 5. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

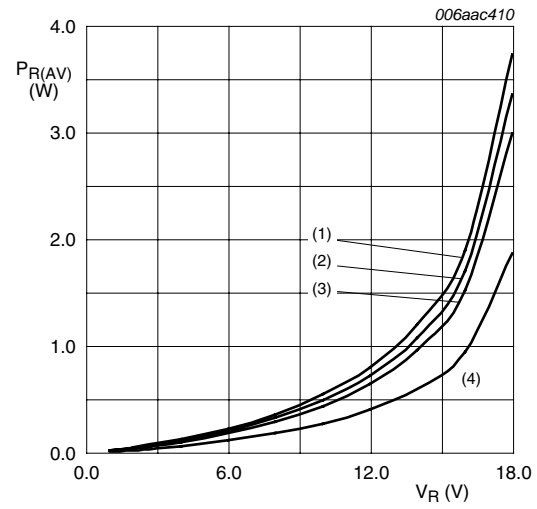
Fig 6. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150\text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

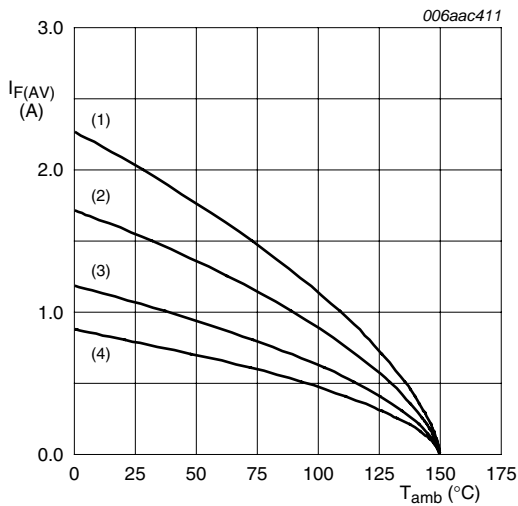
Fig 7. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125\text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig 8. Average reverse power dissipation as a function of reverse voltage; typical values

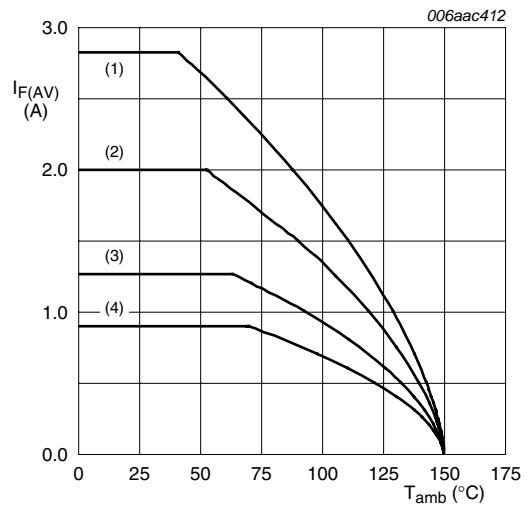


FR4 PCB, standard footprint

$T_j = 150\text{ }^\circ\text{C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 9. Average forward current as a function of ambient temperature; typical values

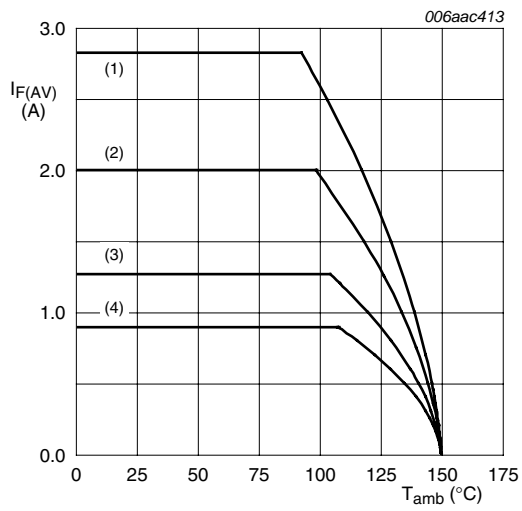


FR4 PCB, mounting pad for cathode 1 cm^2

$T_j = 150\text{ }^\circ\text{C}$

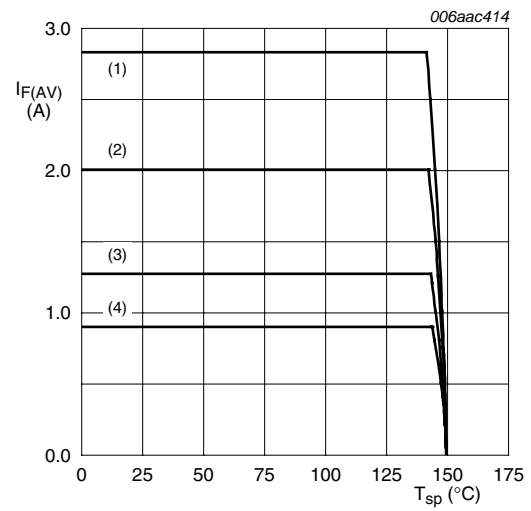
- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3 , standard footprint
 $T_j = 150\text{ }^{\circ}C$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

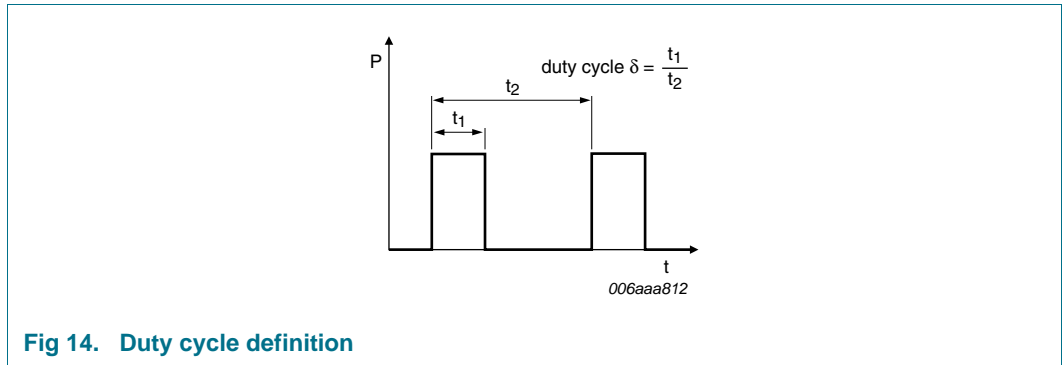
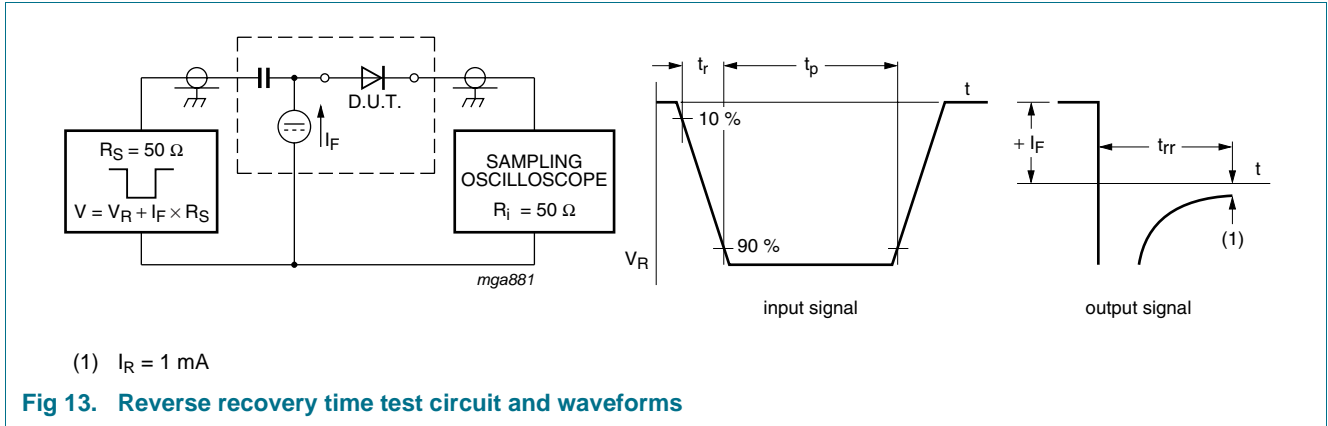
Fig 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ }^{\circ}C$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 12. Average forward current as a function of solder point temperature; typical values

8. Test information



The current ratings for the typical waveforms as shown in [Figure 9](#), [10](#), [11](#) and [12](#) are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

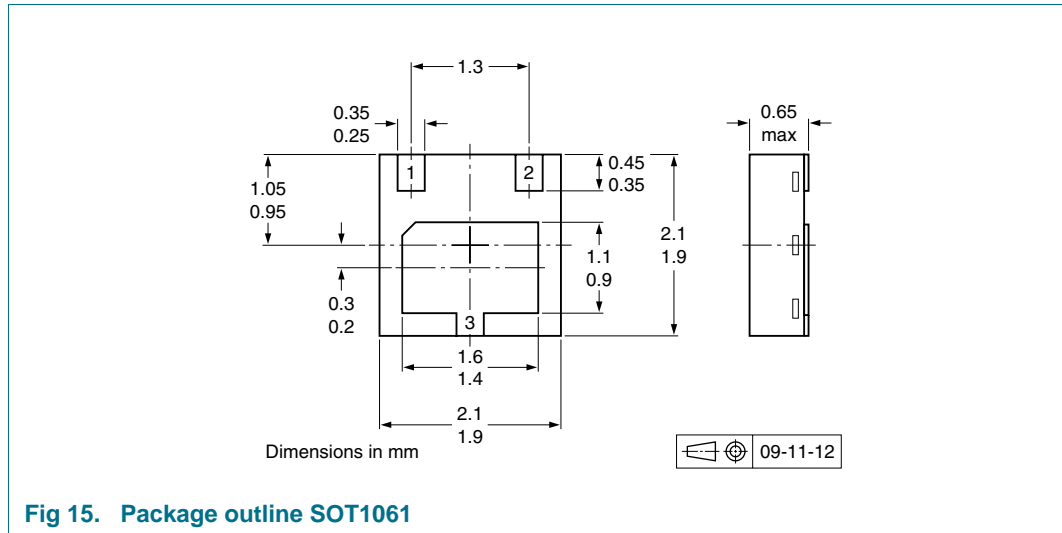


Fig 15. Package outline SOT1061

10. Packing information

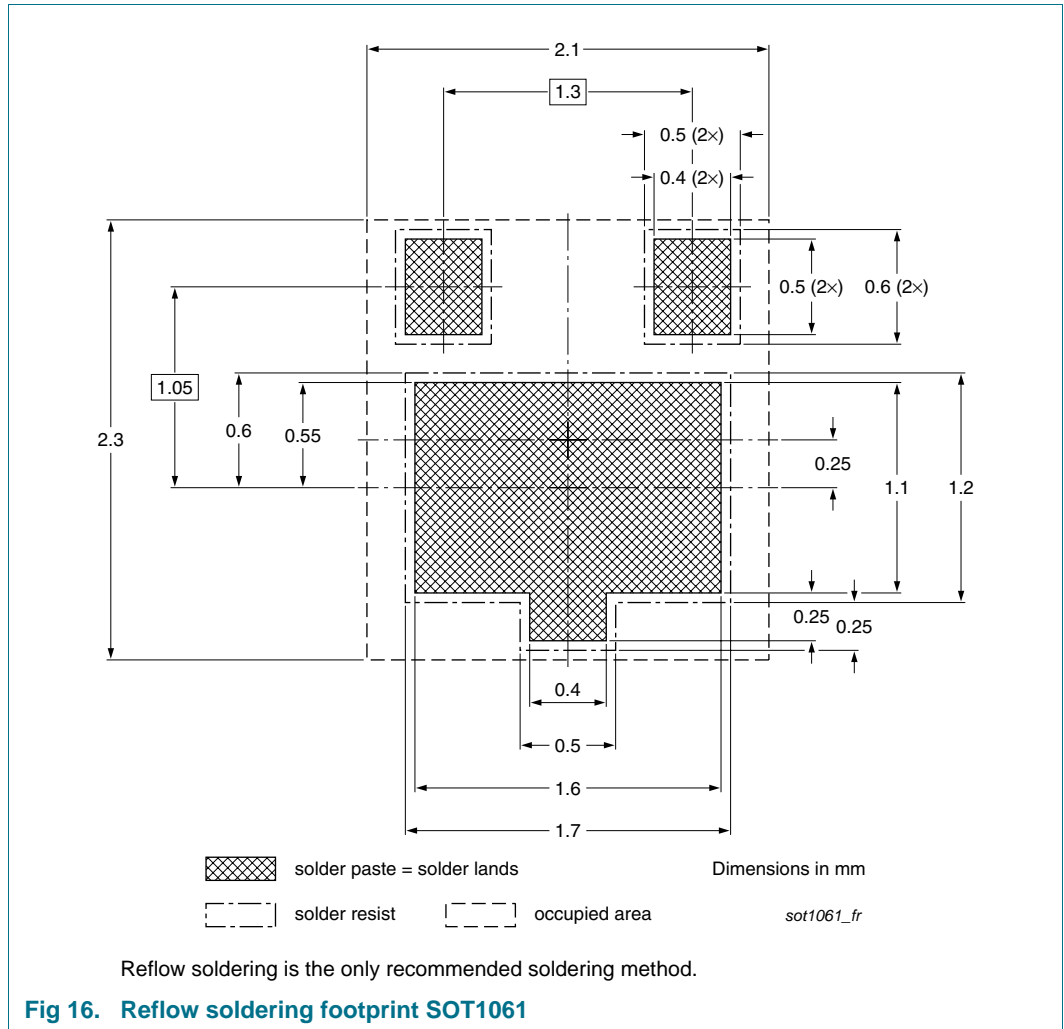
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity
			3000
PMEG2020CPA	SOT1061	4 mm pitch, 8 mm tape and reel	-115

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2020CPA v.1	20100805	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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